FFSH10120ADN-F155

Silicon Carbide Schottky Diode

1200 V, 10 A

Description

Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size and cost.

Features

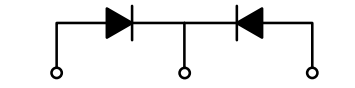
- Max Junction Temperature 175°C
- Avalanche Rated 55 mJ
- High Surge Current Capacity
- Positive Temperature Coefficient
- Ease of Paralleling
- No Reverse Recovery/No Forward Recovery

Applications

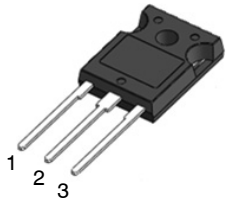
- General Purpose
- SMPS, Solar Inverter, UPS
- Power Switching Circuits

ON Semiconductor®

www.onsemi.com

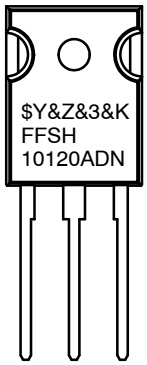


Schottky Diode



TO−247−3LD
CASE 340CH

MARKING DIAGRAM



$Y	= ON Semiconductor Logo
&Z	= Assembly Plant Code
&3	= Numeric Date Code
&K	= Lot Code
FFSH10120ADN	= Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

ABSOLUTE MAXIMUM RATINGS (T_C = 25°C unless otherwise noted) (per leg)

Symbol	Parameter		Value	Unit
V_{RRM}	Peak Repetitive Reverse Voltage		1200	V
E_{AS}	Single Pulse Avalanche Energy (Note 1)		55	mJ
I_F	Continuous Rectified Forward Current @ T_C < 157°C		5* / 10**	A
	Continuous Rectified Forward Current @ T_C < 135°C		8.1* / 16.2**	A
$I_{F, Max}$	Non-Repetitive Peak Forward Surge Current	T_C = 25°C, 10 μs	380	A
		T_C = 150°C, 10 μs	330	A
$I_{F,SM}$	Non-Repetitive Forward Surge Current	Half-Sine Pulse, t_p = 8.3 ms	42	A
$I_{F,RM}$	Repetitive Forward Surge Current	Half-Sine Pulse, t_p = 8.3 ms	21	A
Ptot	Power Dissipation	T_C = 25°C	83	W
		T_C = 150°C	14	W
T_J, T_{STG}	Operating and Storage Temperature Range		−55 to +175	°C
	TO−247 Mounting Torque, M3 Screw		60	Ncm

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
NOTE: * Per leg, ** Per Device
1. E_{AS} of 55 mJ is based on starting T_J = 25°C, L = 0.5 mH, I_{AS} = 15 A, V = 50 V.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max	1.8*/ 0.91**	°C/W

NOTE: * Per leg, ** Per Device

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted) (per leg)

Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
V_F	Forward Voltage	I_F = 5 A, T_C = 25°C	–	1.45	1.75	V
		I_F = 5 A, T_C = 125°C	–	1.7	2.0	
		I_F = 5 A, T_C = 175°C	–	2.0	2.4	
I_R	Reverse Current	V_R = 1200 V, T_C = 25°C	–	–	200	μA
		V_R = 1200 V, T_C = 125°C	–	–	300	
		V_R = 1200 V, T_C = 175°C	–	–	400	
Q_C	Total Capacitive Charge	V = 800 V	–	37	–	nC
C	Total Capacitance	V_R = 1 V, f = 100 kHz	–	337	–	pF
		V_R = 400 V, f = 100 kHz	–	33	–	
		V_R = 800 V, f = 100 kHz	–	26	–	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

ORDERING INFORMATION

Part Number	Top Marking	Package	Shipping
FFSH10120ADN−F155	FFSH10120ADN	TO−247−3LD	30 Units / Tube

TYPICAL CHARACTERISTICS

(T_J = 25°C unless otherwise noted) (per leg)

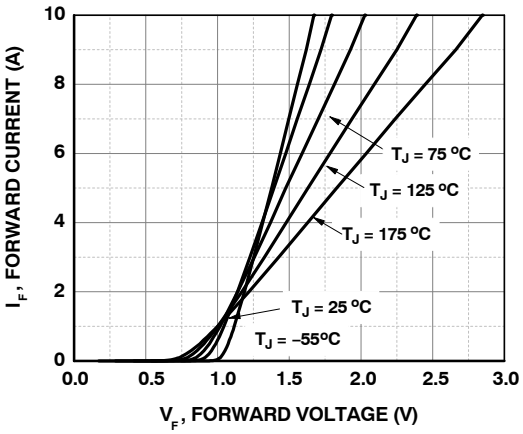


Figure 1. Forward Characteristics

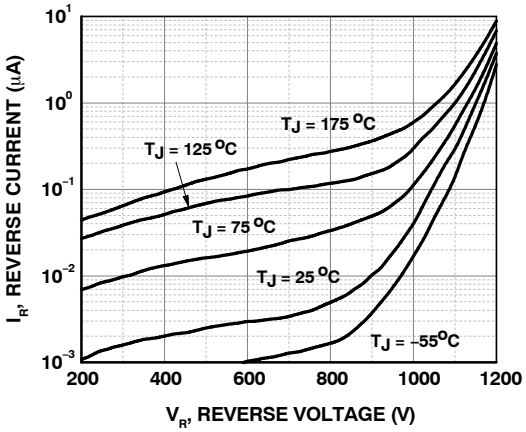


Figure 2. Reverse Characteristics

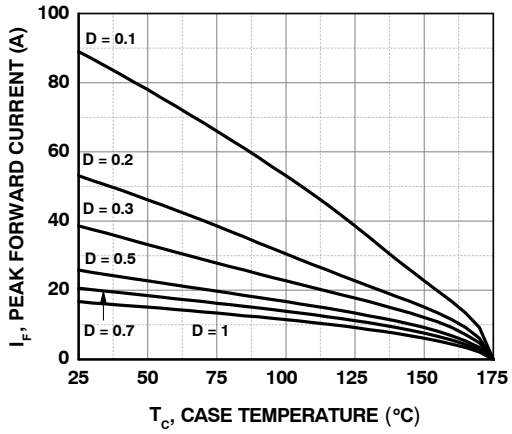


Figure 3. Current Derating

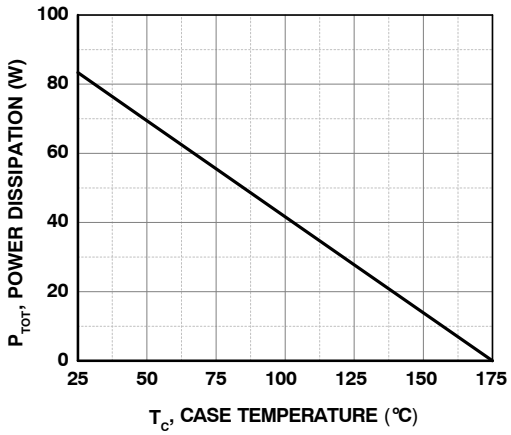


Figure 4. Power Derating

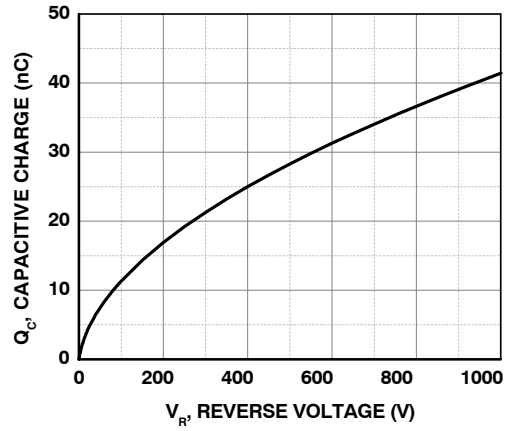


Figure 5. Capacitive Charge vs. Reverse Voltage

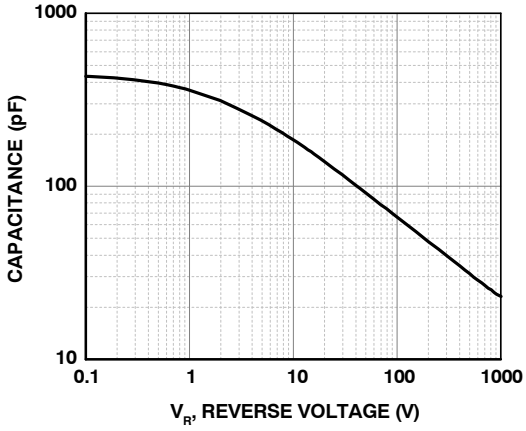


Figure 6. Capacitance vs. Reverse Voltage

TYPICAL CHARACTERISTICS

(T_J = 25°C unless otherwise noted)

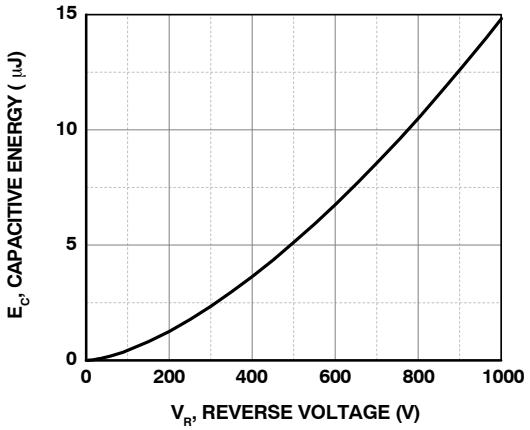


Figure 7. Capacitance Stored Energy

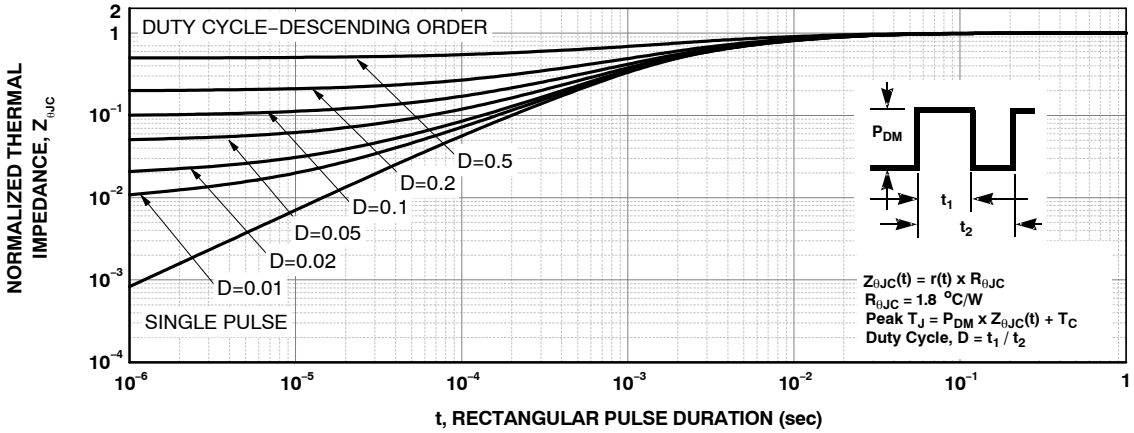


Figure 8. Junction-to-Case Transient Thermal Response Curve

TEST CIRCUIT AND WAVEFORMS

L = 0.5 mH
R < 0.1 Ω
V_{DD} = 50 V
EAVL = 1/2LI2 [$V_{R(AVL)}$ / ($V_{R(AVL)}$ − V_{DD})]
Q1 = IGBT (BV_{CES} > DUT $V_{R(AVL)}$)

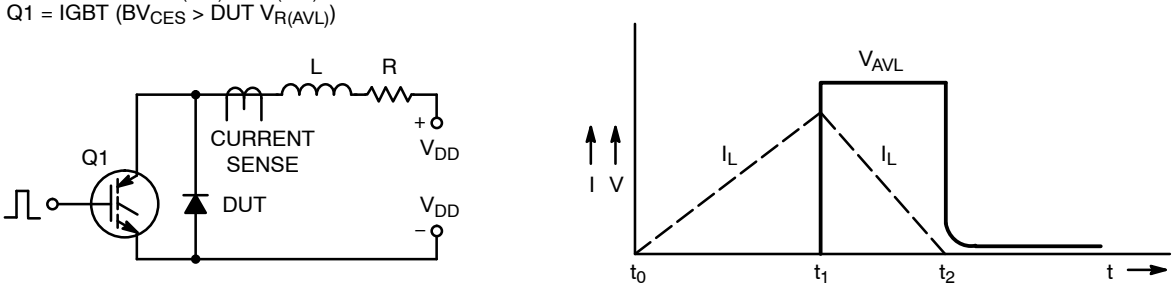


Figure 9. Unclamped Inductive Switching Test Circuit & Waveform

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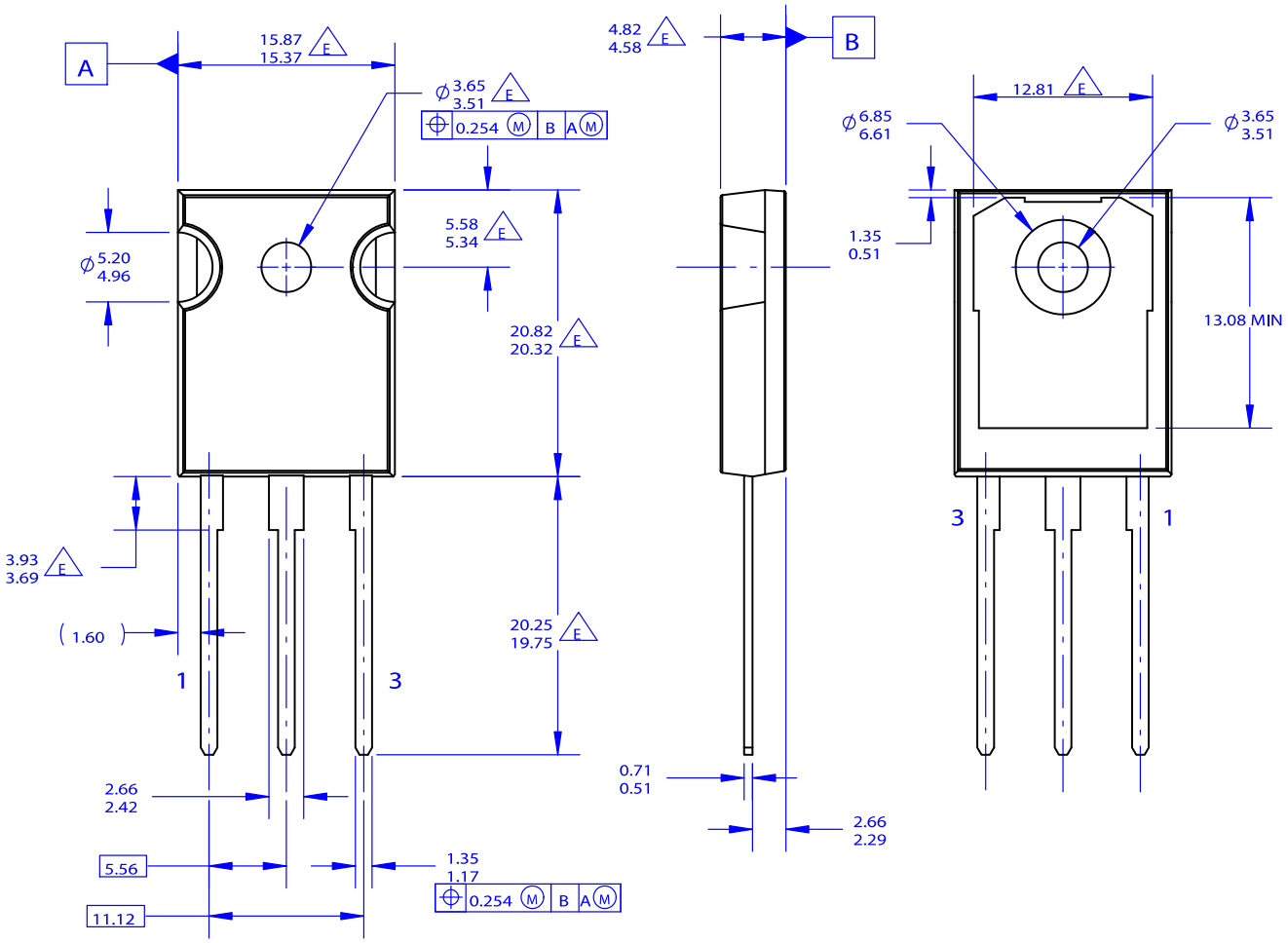

NOTES: UNLESS OTHERWISE SPECIFIED.

A. PACKAGE REFERENCE: JEDEC TO-247, ISSUE E, VARIATION AB, DATED JUNE, 2004.
B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
C. ALL DIMENSIONS ARE IN MILLIMETERS.
D. DRAWING CONFORMS TO ASME Y14.5 - 1994

E DOES NOT COMPLY JEDEC STANDARD VALUE

ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION FROM FAIRCHILD TO247G03 TO ON SEMICONDUCTOR. REQ. BY J. LETTERMAN.	31 OCT 2016

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
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